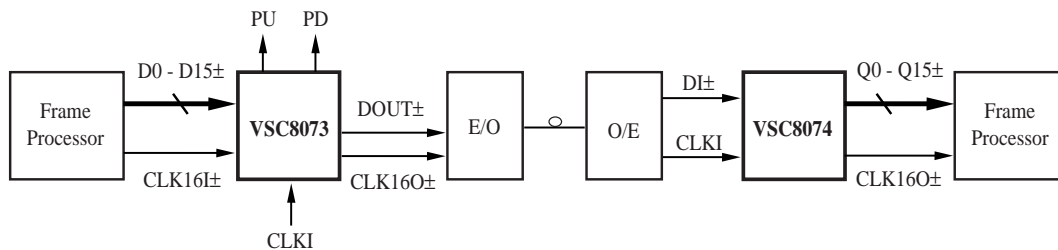


## Features

- Performs 16:1 MUX Between 16 622Mb/s Low-Speed Signals and 10Gb/s/High-Speed Signals
- Fully Differential Low-Speed Interface
- Industry Standard  $-2.0V$  and  $-5.2V$  Power Supplies
- 50 $\Omega$  Output Drive Capability
- Internal Input Terminations
- Integrated Phase-Frequency Detector
- Industry-Standard 80-Pin PQFP Package

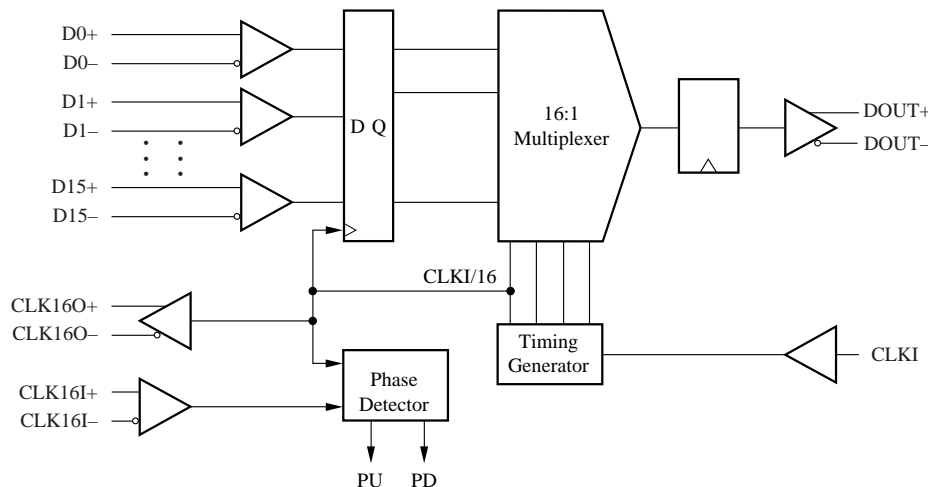
## Typical System Block Diagram



## General Description

The VSC8073 accepts 16 differential ECL 622Mb/s parallel inputs (**D0-D15±**). Using the 10GHz clock input (**CLKI**), the low-speed parallel inputs are multiplexed into a differential 10Gb/s high-speed output (**DOUT±**). In addition to the data inputs, a differential 622MHz clock output (**CLK160±**) is provided. The device operates using  $-5.2V$  and  $-2.0V$  power supplies and is packaged in a thermally-enhanced, standard plastic package.

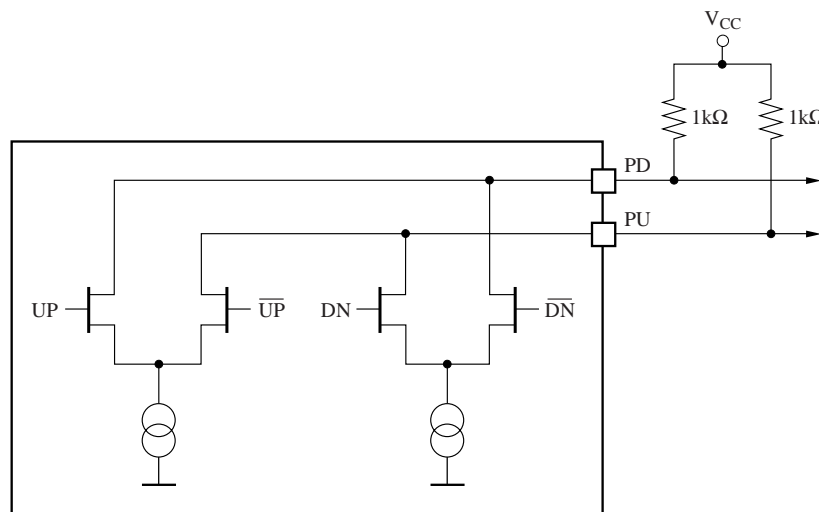
## Functional Block Diagram



## VSC8073 Functional Description

The VSC8073 integrates a 16:1 multiplexer with synchronous timing control with a phase detector. The phase and frequency detector resolves phase timing differences between the frame processor and the bit rate clock, allowing for use with an external Phase Lock-Loop (PLL). The potential difference between PU and PD is proportional to the phase difference between **CLK16I** and internal **CLK/16**. The phase detector gain is 140mv/rad with an external 1k $\Omega$  resistance (see Figure 1).

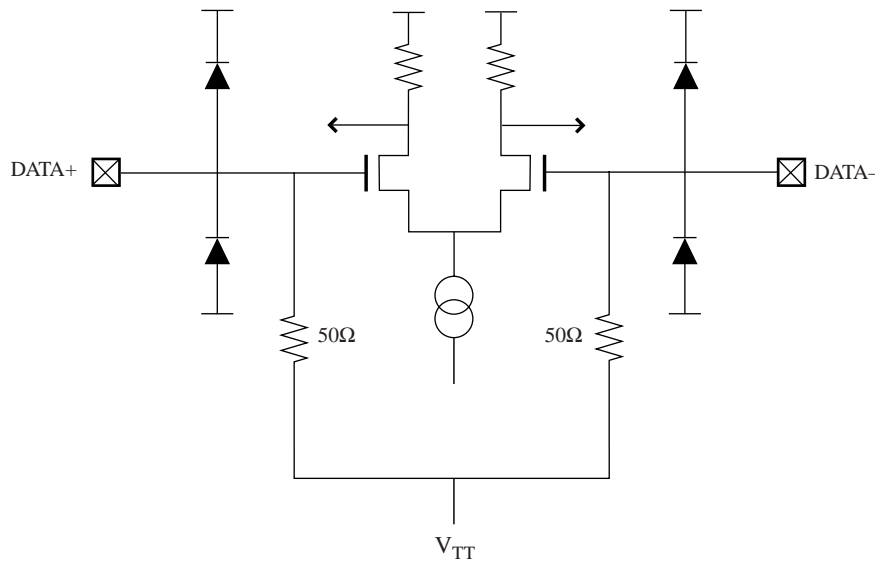
**Figure 1: Phase Detector Outputs**



## Low-Speed Interface

The ECL-compatible parallel data inputs (**D0-D15 $\pm$** ) and parallel data rate clock (**CLK16I $\pm$** ) are provided with on-chip 50 $\Omega$  terminations to  $V_{TT}$ . ECL-compatible divided differential clocks (**CLK16O $\pm$** ) are provided and should be externally terminated with 50 $\Omega$  resistors to  $V_{TT}$ . The low speed interfaces, **Q0-Q15 $\pm$**  and **CLK16O $\pm$** , are realized using ECL levels as defined in Table 2. The recommended load configuration for the outputs is 50 $\Omega$ , shown in Figure 2.

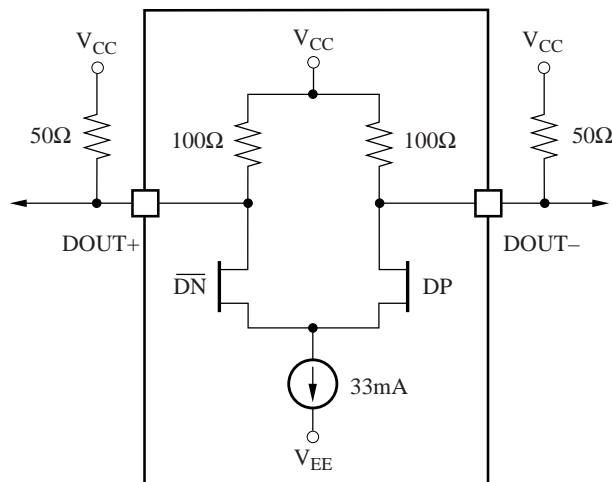
**Figure 2: Low-Speed ECL Input Receiver**



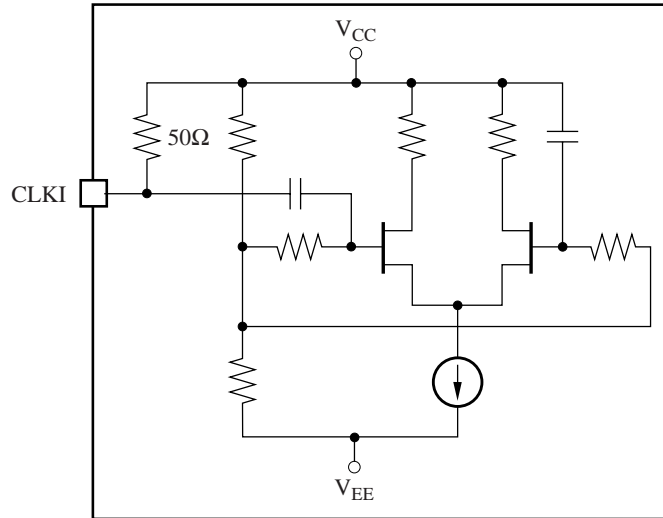
### High-Speed Interface

The high-speed data output drivers are internally terminated through 100Ω resistors to  $V_{CC}$ . The bit rate clock (CLKI) input is internally terminated with a 50Ω termination to  $V_{CC}$ . The serial data outputs (DOUT±) are back-terminated with on-chip 100Ω resistors. The internal output driver and termination schemes for the data outputs and clock input are shown in Figures 3 and 4, respectively. The high-speed differential data out (DOUT±) requirements appear in Table 3. The high-speed clock input (CLKI) requirements appear in Table 4.

**Figure 3: High-Speed Data Output Driver**



**Figure 4: High-Speed Clock Input Receiver**



### Power Supplies

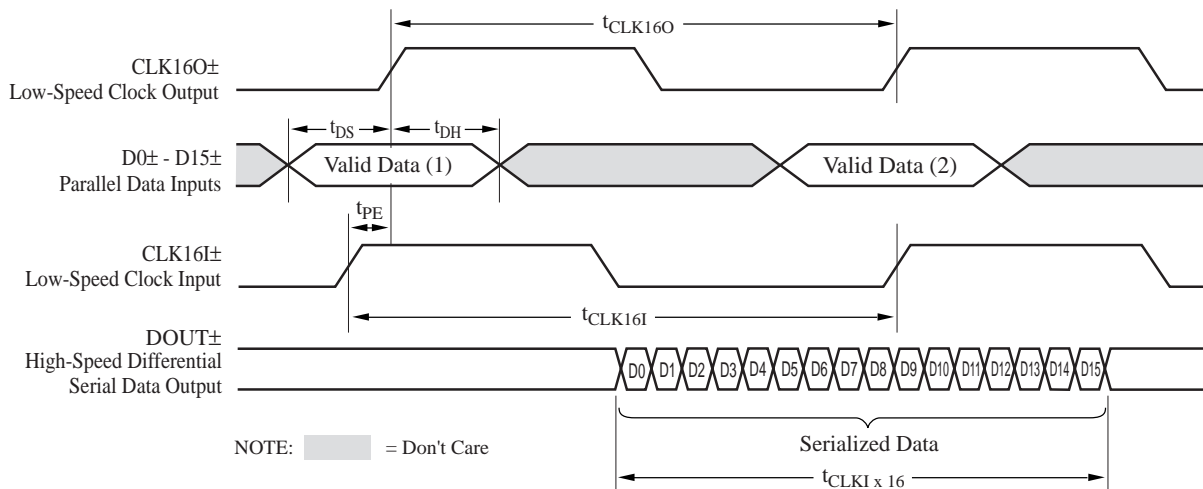
The device is typically operated from a  $-5.2\text{V}$  supply ( $V_{EE}$ ) and  $-2.0\text{V}$  supply ( $V_{TT}$ ).  $V_{CC}$  is typically held at ground potential. Decoupling of the power supplies is a critical element in maintaining proper operation of the part. It is recommended that  $V_{CC}$  be decoupled using a  $0.1\mu\text{F}$  and a  $0.01\mu\text{F}$  capacitor placed in parallel on each  $V_{CC}$  pin as close to the package as possible. If room permits, a  $0.001\mu\text{F}$  capacitor should also be placed in parallel with the  $0.1\mu\text{F}$  and  $0.01\mu\text{F}$  capacitors previously mentioned. Recommended capacitors are low-inductance, ceramic SMT X7R devices. A 0603 package should be used for the  $0.1\mu\text{F}$  capacitor; the  $0.01\mu\text{F}$  and  $0.001\mu\text{F}$  capacitors can be either 0603 or 0403 packages.

**AC Characteristics** (Over Recommended Operating Conditions)

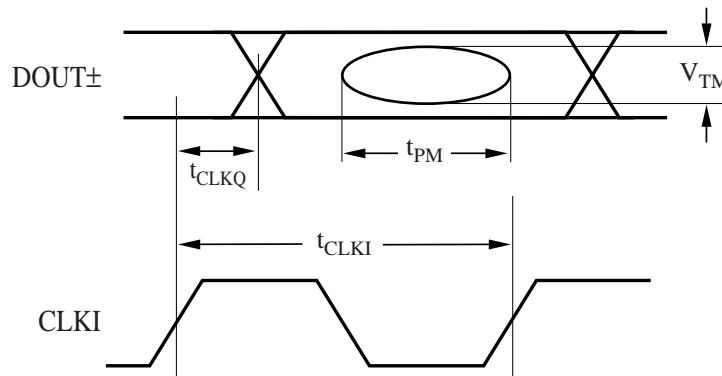
**Table 1: AC Timing Characteristics**

Parameter	Description	Min	Typ	Max	Units	Conditions
$t_{CLK16OR}$ , $t_{CLK16OF}$	CLK16O Rise and Fall Times	—	250	350	ps	See Figure 7, 20 % to 80%
$t_{CLK16IR}$ , $t_{CLK16IF}$	CLK16I Rise and Fall Times	—	300	350	ps	—
$t_{CLKI}$	High-Speed Input Clock Period	—	100.46	—	ps	See Figure 6
$t_{CLK16I}$	CLK16I Period	—	1.607	—	ns	See Figure 5
$t_{CLKQ}$	CLKI to DOUT Delay	—	200	—	ps	See Figure 6
$t_{PE}$	CLK16I to CLK16O Delay	—	50	—	ps	Differential CLK16I, PU = PD (zero on-chip error)
$DC_{HCLK}$	Duty Cycle of High-Speed Clock In	40	—	60	%	—
$DC_{LCLK}$	Duty Cycle of Low-Speed Clock In	40	—	60	%	—
$t_{DOR}$ , $t_{DOF}$	Serial Data Rise and Fall Times	—	35	40	ps	See Figure 7, 20% to 80%
$t_{D0-D15R}$ , $t_{D0-D15F}$	Data Input Rise and Fall Times	—	300	350	ps	—
$t_{DS}$	Data Setup to CLK16O	—	—	300	ps	See Figure 5
$t_{DH}$	Data Hold from CLK16O	300	—	—	ps	See Figure 5
$V_{TM}$	Threshold Margin	500	600	—	mV	See Figure 6
$t_{PM}$	Phase Margin	230	260	—	degrees	At $(2^{31} - 1)$ PRBS. See Figure 6.
$K_{PD}$	Phase Detector Gain	—	140	—	mV/rad	1 radian ~ 16ps

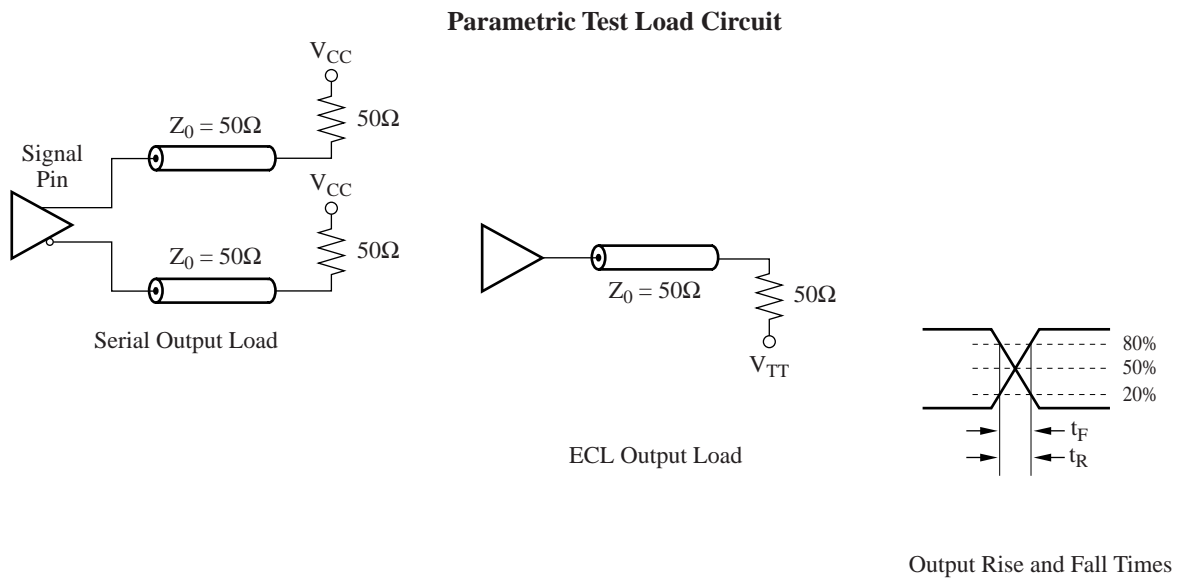
**Figure 5: VSC8073 AC Timing Waveforms**



**Figure 6: VSC8073 Output Data Eye**



**Figure 7: Parametric Measurement Information**



## DC Characteristics (Over Recommended Operating Conditions)

**Table 2: ECL Inputs/Outputs**

Parameter	Description	Min	Typ	Max	Units	Conditions
V <sub>OH</sub>	Output HIGH Voltage	-1100	—	-700	mV	50Ω to V <sub>TT</sub> Load
V <sub>OL</sub>	Output LOW Voltage	V <sub>TT</sub>	—	-1620	mV	50Ω to V <sub>TT</sub> Load
V <sub>IH</sub>	Input HIGH Voltage	-1165	—	-700	mV	—
V <sub>IL</sub>	Input LOW Voltage	V <sub>TT</sub>	—	-1475	mV	—
I <sub>IH</sub>	Input HIGH Current	—	—	32	mA	V <sub>IN</sub> = -700mV, V <sub>TT</sub> = -2.1V
I <sub>IL</sub>	Input LOW Current	—	—	9	mA	V <sub>IN</sub> = -1750mV, V <sub>TT</sub> = -2.1V

**Table 3: High-Speed Data Outputs**

Parameter	Description	Min	Typ	Max	Units	Conditions
V <sub>OH</sub>	Output HIGH Voltage	-200	—	-100	mV	External to 50Ω to V <sub>CC</sub>
V <sub>OL</sub>	Output LOW Voltage	-1100	-900	-750	mV	External to 50Ω to V <sub>CC</sub>
I <sub>OH</sub>	Output HIGH Current	—	3	7	mA	—
I <sub>OL</sub>	Output LOW Current	—	30	37	mA	—
Z <sub>0</sub>	Output Impedance	80	100	120	Ω	DC

**Table 4: High-Speed Clock Inputs**

Parameter	Description	Min	Typ	Max	Units	Conditions
V <sub>IN</sub>	Input Swing, Single-Ended	—	500	—	mV	Peak-to-Peak
R <sub>INDC</sub>	DC Value of CLKI	-1.8	—	+1.8	V	—
R <sub>TERM</sub>	Termination Resistor	40	50	60	Ω	—

**Table 5: Power Dissipation**

Parameter	Description	Min	Typ	Max	Units	Conditions
I <sub>EE</sub>	Supply Current	—	700	TBD	mA	Outputs Open
I <sub>TT</sub>	Termination Current	—	—	860	mA	All Differential Inputs Terminated. R <sub>T</sub> = 40Ω
P <sub>D</sub>	Power Dissipation	—	4.5	—	W	—

## Absolute Maximum Ratings<sup>(1)</sup>

ECL Power Supply Voltage, ( $V_{EE}$ ) .....	-7.0V to +0.7V
Termination Voltage, ECL Input ( $V_{TT}$ ) .....	-2.5V to +0.5V
DC Input Voltage (low-speed inputs, D0-D15 $\pm$ ) .....	$V_{TT} - 2.5V$ to +0.5V
Input Voltage, CLKI <sup>(2)</sup> .....	-2.8V to +2.8V
Case Temperature Under Bias .....	-55 $^{\circ}$ to +125 $^{\circ}$ C
Storage Temperature .....	-65 $^{\circ}$ C to +150 $^{\circ}$ C

## Recommended Operating Conditions

Power Supply Voltage ( $V_{EE}$ ) .....	-5.2V $\pm$ 5%
Termination Supply Voltage ( $V_{TT}$ ) <sup>(3)</sup> .....	-2.0V $\pm$ 5%
Operating Case Temperature Range ( $T$ ) <sup>(4)</sup> .....	0 $^{\circ}$ to 85 $^{\circ}$ C

Notes: (1) CAUTION: Stresses listed under "Absolute Maximum Ratings" may be applied to devices one at a time without causing permanent damage. Functionality at or exceeding the values listed is not implied. Exposure to these values for extended periods may affect device reliability.

(2) Static voltage on CLKI must be within -1.8V to +1.8V.

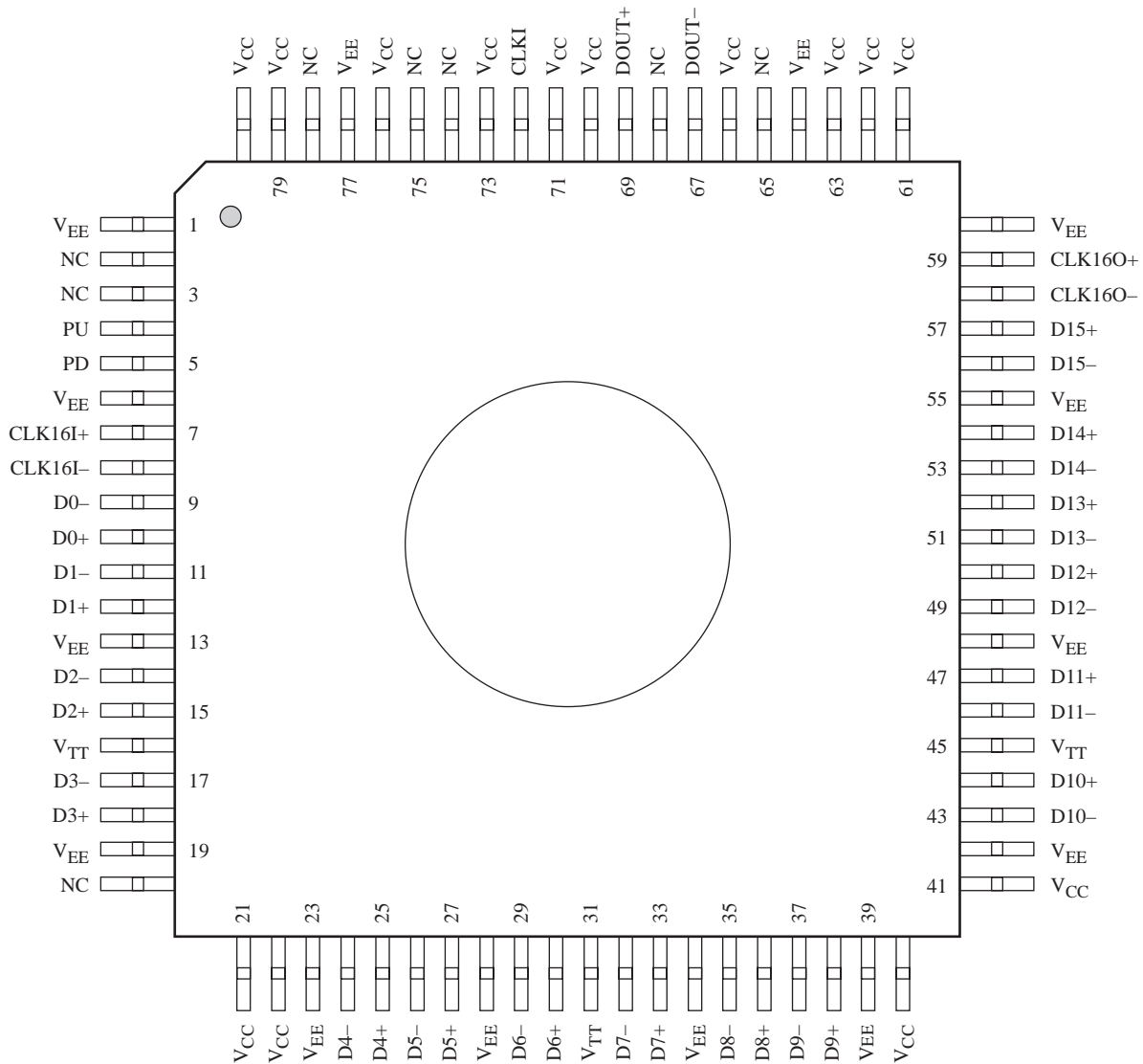
(3) CAUTION: Do not apply  $V_{TT}$  prior to  $V_{EE}$ .

(4) Lower limit is ambient temperature and upper limit is case temperature.



## Package Pin Descriptions

Figure 8: Pin Diagram



Top View

**Table 6: Pin Identification**

<i>Pin</i>	<i>I/O</i>	<i>Pin Description</i>
9-12, 14, 15, 17, 18 24-27, 29, 30, 32, 33, 35-38, 43, 44, 46, 47, 49-54, 56, 57	D0-D15±	INPUT—DIFFERENTIAL ECL: Parallel data presented to this port is clocked into the device. The timing of this data is relative to the CLK16O output.
72	CLKI	INPUT—HIGH-SPEED CLOCK: Bit rate input clock. This clock is terminated with 50Ω resistors to V <sub>CC</sub> , and is AC-coupled on chip.
7, 8	CLK16I±	INPUT—DIFFERENTIAL ECL: Parallel data rate clock.
67, 69	DOUT±	OUTPUT—DIFFERENTIAL HIGH SPEED: Serial data output stream. DOUT+ and DOUT– should be terminated with 50Ω resistors to ground at the load.
58, 59	CLK16O±	OUTPUT—DIFFERENTIAL ECL: Bit rate clock divided by 16.
4, 5	PU, PD	OUTPUT—ANALOG: Phase detector outputs.
21, 22, 40, 41, 61-63, 66, 70, 71, 73, 76, 79, 80	V <sub>CC</sub>	GROUND
1, 6, 13, 19, 23, 28, 34, 39, 42, 48, 55, 60, 64, 77	V <sub>EE</sub>	POWER SUPPLY: –5.2 nominal.
16, 31, 45	V <sub>TT</sub>	POWER SUPPLY: –2.0V nominal.
2, 3, 20, 65, 68, 74, 75, 78	NC	Do not connect, leave open.

**Table 7: Pin Descriptions**

<i>Pin Number</i>	<i>Pin Name</i>	<i>I/O</i>	<i>Level</i>	<i>Description</i>
1	V <sub>EE</sub>	I	–5.2V nom	Power supply at –5.2V nominal
2	NC	NA	NA	Do not connect, leave open.
3	NC	NA	NA	Do not connect, leave open.
4	PU	O	—	Phase detector analog output
5	PD	O	—	Phase detector analog output
6	V <sub>EE</sub>	I	–5.2V nom	Power supply at –5.2V nominal
7	CLK16I+	I	ECL	Differential divide by 16 clock input
8	CLK16I–	I	ECL	Differential divide by 16 clock input
9	D0–	I	ECL	Low-speed differential parallel data
10	D0+	I	ECL	Low-speed differential parallel data
11	D1–	I	ECL	Low-speed differential parallel data

**Table 7: Pin Descriptions**

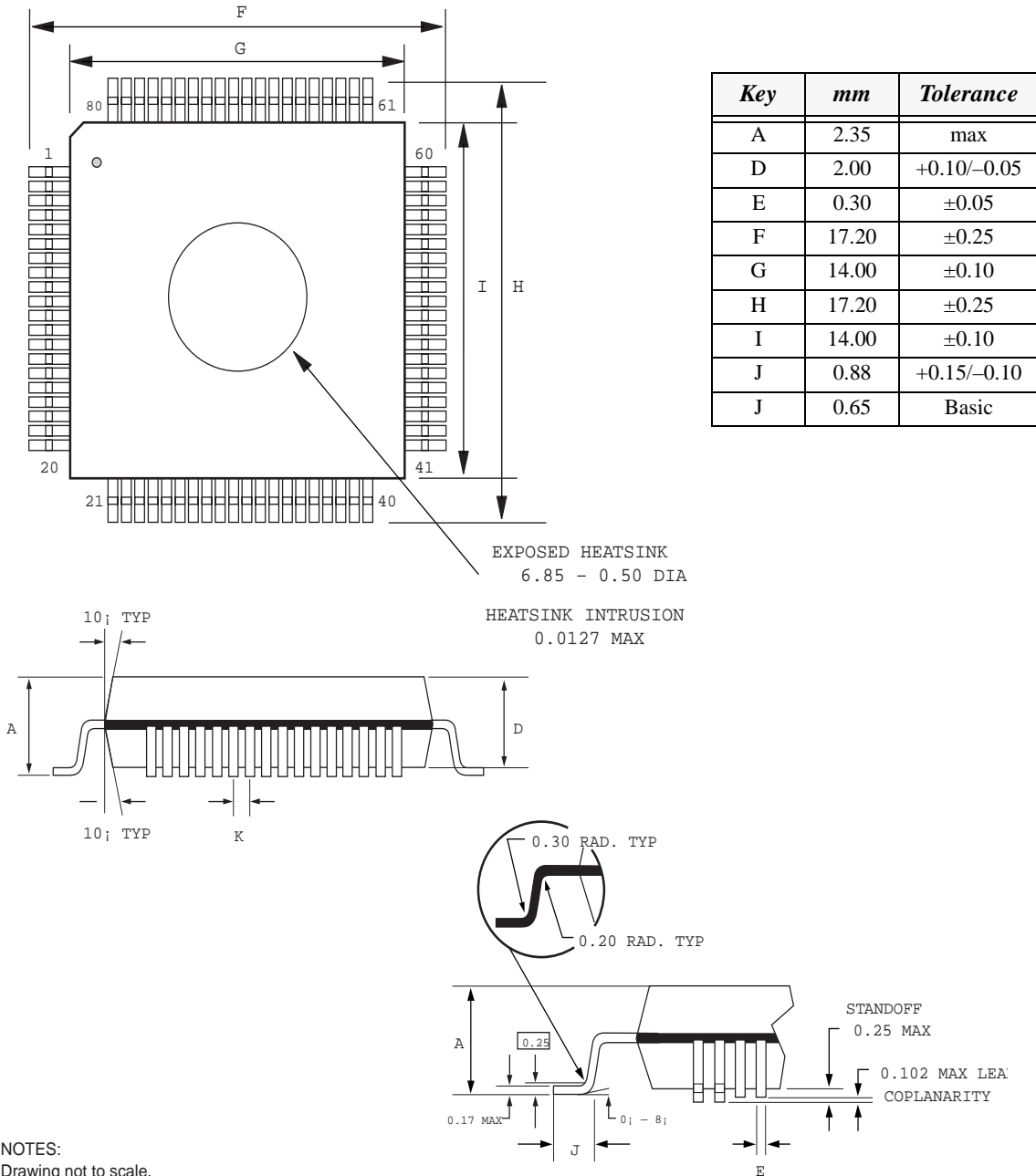
<i>Pin Number</i>	<i>Pin Name</i>	<i>I/O</i>	<i>Level</i>	<i>Description</i>
12	D1+	I	ECL	Low-speed differential parallel data
13	V <sub>EE</sub>	I	-5.2V	Power at -5.2V nominal
14	D2-	I	ECL	Low-speed differential parallel data
15	D2+	I	ECL	Low-speed differential parallel data
16	V <sub>TT</sub>	I	-2.0V	Power at -2.0V nominal
17	D3-	I	ECL	Low-speed differential parallel data
18	D3+	I	ECL	Low-speed differential parallel data
19	V <sub>EE</sub>	I	-5.2V	Power at -5.2V nominal
20	NC	NA	NA	Do not connect, leave open
21	V <sub>CC</sub>	I	GND	Ground
22	V <sub>CC</sub>	I	GND	Ground
23	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
24	D4-	I	ECL	Low-speed differential parallel data
25	D4+	I	ECL	Low-speed differential parallel data
26	D5-	I	ECL	Low-speed differential parallel data
27	D5+	I	ECL	Low-speed differential parallel data
28	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
29	D6-	I	ECL	Low-speed differential parallel data
30	D6+	I	ECL	Low-speed differential parallel data
31	V <sub>TT</sub>	I	-2.0V nom	Power supply at -2.0V nominal
32	D7-	I	ECL	Low-speed differential parallel data
33	D7+	I	ECL	Low-speed differential parallel data
34	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
35	D8-	I	ECL	Low-speed differential parallel data
36	D8+	I	ECL	Low-speed differential parallel data
37	D9-	I	ECL	Low-speed differential parallel data
38	D9+	I	ECL	Low-speed differential parallel data
39	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
40	V <sub>CC</sub>	I	GND	Ground
41	V <sub>CC</sub>	I	GND	Ground
42	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
43	D10-	I	ECL	Low-speed differential parallel data
44	D10+	I	ECL	Low-speed differential parallel data
45	V <sub>TT</sub>	I	-2.0V nom	Power supply at -2.0V nominal
46	D11-	I	ECL	Low-speed differential parallel data
47	D11+	I	ECL	Low-speed differential parallel data

**Table 7: Pin Descriptions**

<i>Pin Number</i>	<i>Pin Name</i>	<i>I/O</i>	<i>Level</i>	<i>Description</i>
48	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
49	D12-	I	ECL	Low-speed differential parallel data
50	D12+	I	ECL	Low-speed differential parallel data
51	D13-	I	ECL	Low-speed differential parallel data
52	D13+	I	ECL	Low-speed differential parallel data
53	D14-	I	ECL	Low-speed differential parallel data
54	D14+	I	ECL	Low-speed differential parallel data
55	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
56	D15-	I	ECL	Low-speed differential parallel data
57	D15+	I	ECL	Low-speed differential parallel data
58	CLK16O-	O	ECL	Differential divide by 16 clock output
59	CLK16O+	O	ECL	Differential divide by 16 clock output
60	VEE	I	-5.2V nom	Power supply at -5.2V nominal
61	V <sub>CC</sub>	I	GND	Ground
62	V <sub>CC</sub>	I	GND	Ground
63	V <sub>CC</sub>	I	GND	Ground
64	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
65	NC	NA	NA	Do not connect, leave open
66	V <sub>CC</sub>	I	GND	Ground
67	DOUT-	O	HS	High-speed differential data out
68	NC	NA	NA	Do not connect, leave open
69	DOUT+	O	HS	High-speed differential data out
70	V <sub>CC</sub>	I	GND	Ground
71	V <sub>CC</sub>	I	GND	Ground
72	CLKI	I	HS	High-speed clock input
73	V <sub>CC</sub>	I	GND	Ground
74	NC	NA	NA	Do not connect, leave open
75	NC	NA	NA	Do not connect, leave open
76	V <sub>CC</sub>	I	GND	Ground
77	V <sub>EE</sub>	I	-5.2V nom	Power supply at -5.2V nominal
78	NC	NA	NA	Do not connect, leave open
79	V <sub>CC</sub>	I	GND	Ground
80	V <sub>CC</sub>	I	GND	Ground

## Package Information

80-Pin PQFP Package Drawing



NOTES:  
Drawing not to scale.  
All units in mm unless otherwise noted.

## Package Thermal Conditions

This package has been enhanced with a copper heat slug to provide a low thermal resistance path from the die to the exposed surface of the heat spreader. Refer to Table 8 for thermal resistance.

**Table 8: Thermal Resistance**

Symbol	Description	°C/W
$\theta_{JC}$	Thermal resistance from junction-to-case.	2.2
$\theta_{CA}$	Thermal resistance from case-to-ambient with no airflow, including conduction through the leads.	25.8
$\theta_{JA}$	Thermal resistance from junction-to-ambient	28

## Thermal Resistance with Airflow

Table 9 shows the thermal resistance with airflow. This thermal resistance value reflects all the thermal paths including through the leads in an environment where the leads are exposed. The temperature difference between the ambient airflow temperature and the case temperature should be the worst-case power of the device multiplied by the thermal resistance.

**Table 9: Thermal Resistance with Airflow**

Airflow (lfpm)	$\theta_{CA}$ (°C/W)
100	24
200	21
400	19
600	17

## Maximum Ambient Temperature Without Heatsink

The worst-case ambient temperature without the use of a heatsink is given by:

$$T_{A(MAX)} = T_{C(MAX)} - P_{(MAX)} \theta_{CA}$$

where,

$\theta_{CA}$  = Theta case-to-ambient at appropriate airflow

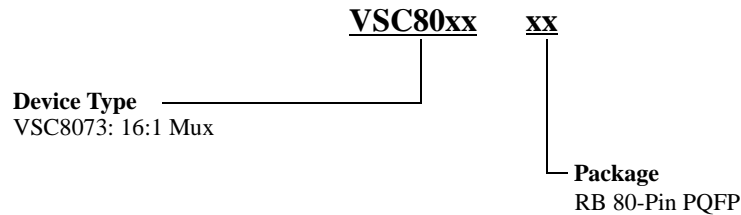
$T_{A(MAX)}$  = Ambient air temperature

$T_{C(MAX)}$  = Case temperature (85°C)

$P_{(MAX)}$  = Power (4.5W)

## Ordering Information

The order number for this product is formed by a combination of the device number, and package type.



## Notice

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